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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. WATANABE ET AL.

Serial No.: 09/462,796

Filed: January 13, 2000

For: SEMICONDUCTOR DEVICE, MOUNTING STRUCTURE
THEREOF AND METHOD OF FABRICATION THEREOF

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V. Vannell

PRELIMINARY AMENDMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

October 11, 2000

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel ~~claims 1 and 8~~ without prejudice or disclaimer and amend claims 6, 7, 20 and 21 as follows:

A1
6. (Amended) A semiconductor device according to [any one of claims 1-5] claim 2, wherein a base material of said pyramidal bump electrodes is made of [hard] an electrode material selected from a group consisting of nickel[, Ni] and copper.

7. (Amended) A semiconductor device according to [any one of claims 1 to 5] claim 3, wherein a base material of said pyramidal bump electrodes is made of [soft] an electrode material selected from a group consisting of nickel and [soft] copper[, Cu].

A2
Cmt
20. (Amended) A mounting structure according to [any one of claims 8 to 19] claim 9, wherein a base material of said pyramidal bump electrodes in said semiconductor device is made